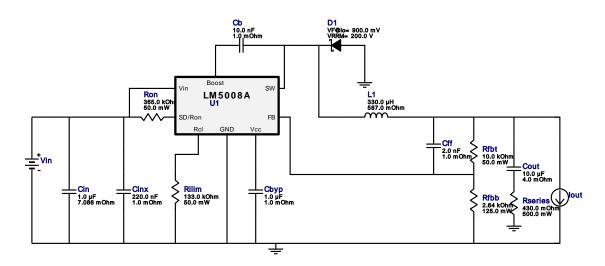


VinMin = 36.0V VinMax = 90.0V Vout = 12.0V lout = 0.35A Device = LM5008AMM/NOPB Topology = Buck Created = 2025-07-15 22:45:13.595 BOM Cost = \$2.63 BOM Count = 6 Total Pd = 0.85W

WEBENCH® Design Report

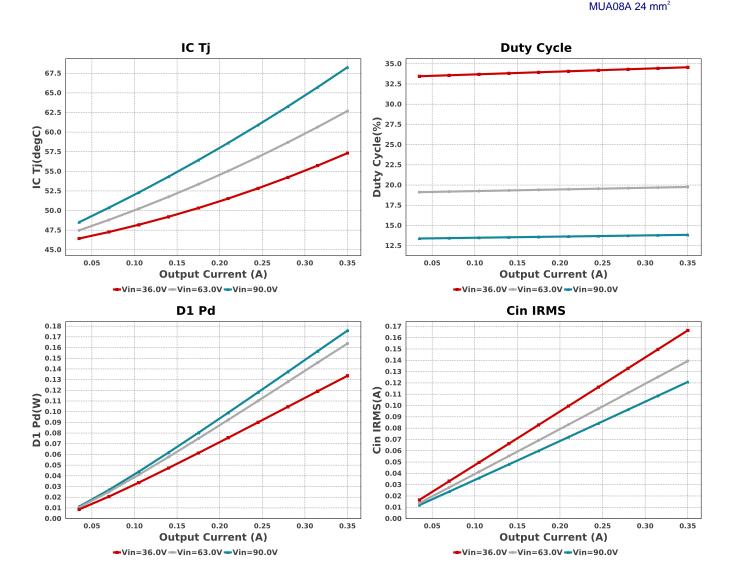
Design: 4 LM5008AMM/NOPB LM5008AMM/NOPB 36V-90V to 12.00V @ 0.35A

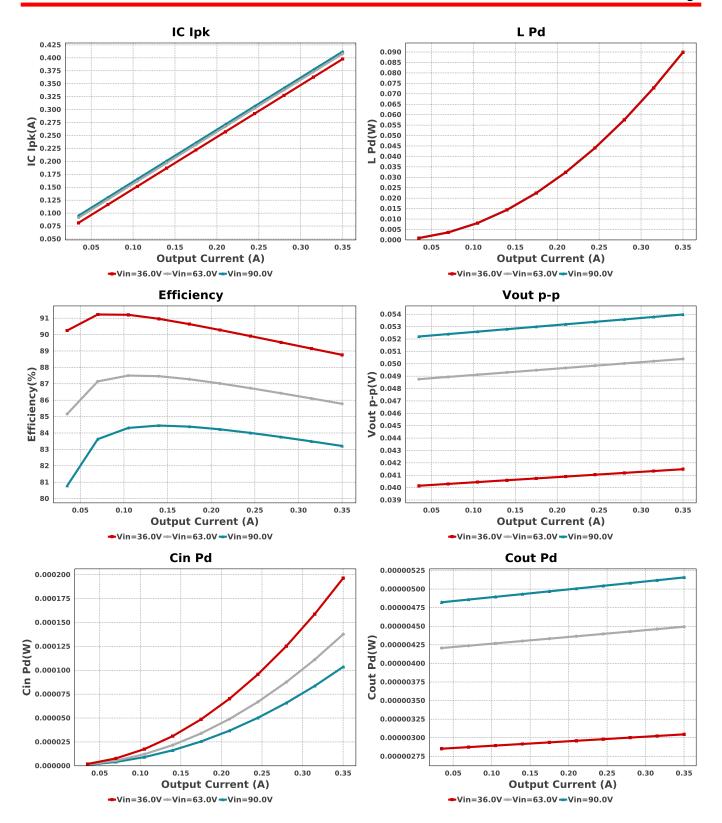


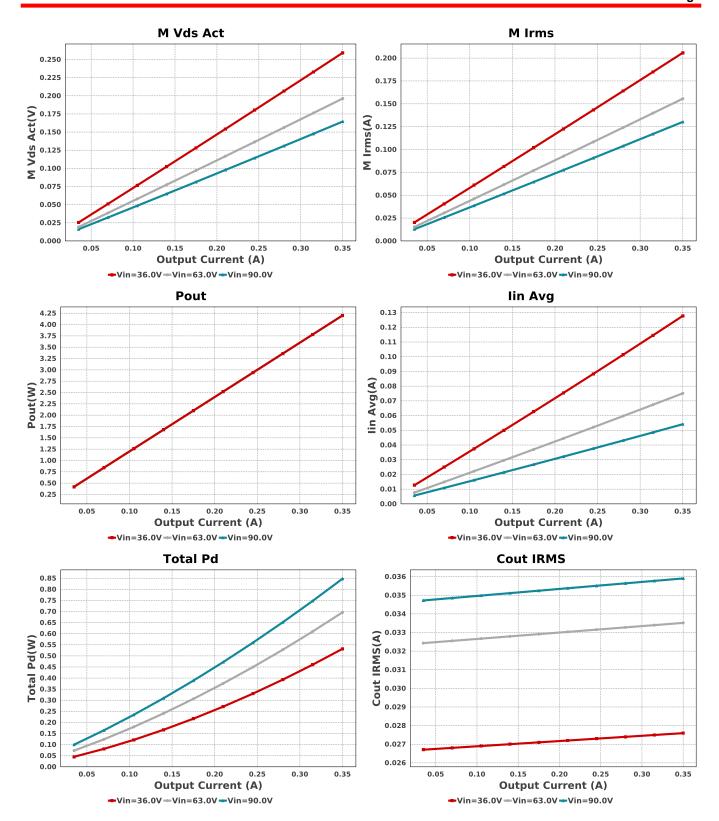
Electrical BOM

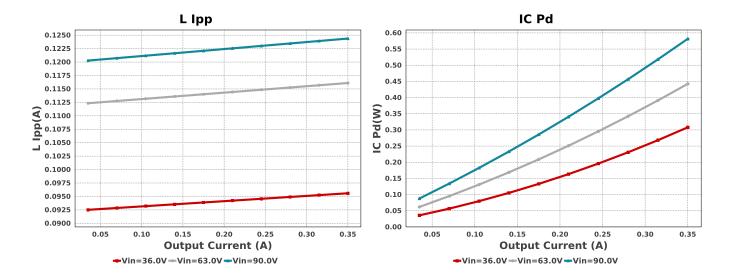
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cb	MuRata	GRM155R71H103KA88D Series= X7R	Cap= 10.0 nF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 0.0 A	1	\$0.01	0402 3 mm ²
Cbyp	Taiyo Yuden	EMK107B7105KA-T Series= X7R	Cap= 1.0 uF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	\$0.01	0603 5 mm ²
Cff	MuRata	GRM1885C1H202JA01D Series= C0G/NP0	Cap= 2.0 nF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 0.0 A	1	\$0.02	0603 5 mm ²
Cin	MuRata	GRM55DR72E105KW01L Series= X7R	Cap= 1.0 uF ESR= 7.086 mOhm VDC= 250.0 V IRMS= 2.0605 A	1	\$0.35	2220_200 54 mm ²
Cinx	MuRata	GRM21AR72A224KAC5L Series= X7R	Cap= 220.0 nF ESR= 1.0 mOhm VDC= 100.0 V IRMS= 0.0 A	1	\$0.08	0805 7 mm ²
Cout	MuRata	GRM21BR61E106MA73L Series= X5R	Cap= 10.0 uF ESR= 4.0 mOhm VDC= 25.0 V IRMS= 2.8 A	1	\$0.04	0805 7 mm ²
D1	SMC Diode Solutions	SK220ATR	VF@Io= 900.0 mV VRRM= 200.0 V	1	\$0.06	SMA 37 mm ²
L1	Wurth Elektronik	7447720331	L= 330.0 μH 587.0 mOhm	1	\$0.55	WE-TI_8095 96 mm ²
Rfbb	Yageo	RT0805BRD072K64L Series=?	Res= 2.64 kOhm Power= 125.0 mW Tolerance= 0.1%	1	\$0.05	0805 7 mm ²
Rfbt	Yageo	RC0201FR-0710KL Series= ?	Res= 10.0 kOhm Power= 50.0 mW Tolerance= 1.0%	1	\$0.01	0201 2 mm ²

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Rilim	Yageo	RC0201FR-07133KL Series= ?	Res= 133.0 kOhm Power= 50.0 mW Tolerance= 1.0%	1	\$0.01	0201 2 mm ²
Ron	Yageo	RC0201FR-07365KL Series= ?	Res= 365.0 kOhm Power= 50.0 mW Tolerance= 1.0%	1	\$0.01	0201 2 mm ²
Rseries	Rohm	MCR25JZHFLR430 Series= MCR25	Res= 430.0 mOhm Power= 500.0 mW Tolerance= 1.0%	1	\$0.03	1210 15 mm ²
U1	Texas Instruments	LM5008AMM/NOPB	Switcher	1	\$1.39	MUADOA OA mara²









Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	120.861 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	103.51 μW	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	35.904 mA	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	5.156 μW	Capacitor	Output capacitor power dissipation
5.	D1 Pd	175.87 mW	Diode	Output Diode Power Dissipation
6.	IC lpk	412.187 mA	IC	Peak switch current in IC
7.	IC Pd	581.69 mW	IC	IC power dissipation
8.	IC Ti	68.268 degC	IC	IC junction temperature
9.	IC Tolerance	50.0 mV	IC	IC Feedback Tolerance
10.	ICThetaJA	40.0 degC/W	IC	IC junction-to-ambient thermal resistance
11.	lin Avg	54.13 mA	IC	Average input current
12.	L lpp	124.374 mA	Inductor	Peak-to-peak inductor ripple current
13.	L Pd	89.884 mW	Inductor	Inductor power dissipation
14.	M1 Irms	130.206 mA	Mosfet	Q lavg
15.	M Vds Act	164.448 mV	Mosfet	Voltage drop across the MosFET
16.	Cin Pd	103.51 μW	Power	Input capacitor power dissipation
17.		5.156 μW	Power	Output capacitor power dissipation
18.	D1 Pd	175.87 mW	Power	Output Diode Power Dissipation
19.	IC Pd	581.69 mW	Power	IC power dissipation
20.		89.884 mW	Power	Inductor power dissipation
20. 21.		847.552 mW	Power	Total Power Dissipation
22.	BOM Count	6	System	Total Design BOM count
۷۷.	BOW Count	U	Information	Total Design Bow Count
23.	Duty Cycle	13.84 %		Duty cycle
23.	Duty Cycle	13.04 %	System Information	Duty cycle
24	⊏#isisss.	02 200 0/		Ctoody state officiancy
24.	Efficiency	83.209 %	System	Steady state efficiency
0-	Es al Debat	2	Information	Total Foot Brist Associate BOM associate
25.	FootPrint	264.0 mm ²	System	Total Foot Print Area of BOM components
	_		Information	
26.	Frequency	263.014 kHz	System	Switching frequency
			Information	
27.	lout	350.0 mA	System	lout operating point
			Information	
28.	Mode	CCM	System	Conduction Mode
			Information	
29.	Pout	4.2 W	System	Total output power
			Information	
30.	Total BOM	\$2.625	System	Total BOM Cost
			Information	
31.	Vin	90.0 V	System	Vin operating point
			Information	
32.	Vout	12.0 V	System	Operational Output Voltage
			Information	
33.	Vout Actual	11.97 V	System	Vout Actual calculated based on selected voltage divider resistors
			Information	·
34.	Vout Tolerance	2.889 %	System	Vout Tolerance based on IC Tolerance (no load) and voltage divide
			Information	resistors if applicable
	Vout p-p	53.978 mV	System	Peak-to-peak output ripple voltage
35.				

Design Inputs

Name	Value	Description	
lout	350.0 m	Maximum Output Current	
VinMax	90.0	Maximum input voltage	
VinMin	36.0	Minimum input voltage	
Vout	12.0	Output Voltage	
base_pn	LM5008A	Base Product Number	
source	DC	Input Source Type	
Та	45.0	Ambient temperature	
UserFsw	300.0 k	Customer Selected Frequency	

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

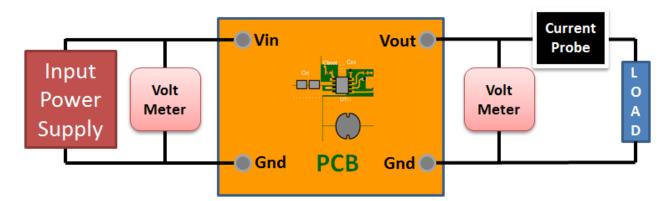
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 36.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum lout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

- 1. For a Constant On Time device to be stable, we need to provide a ripple at the feedback comparator. There are various methods to implement the ripple. Depending on the circuit complexity vs. the allowable ripple, we have three options to choose from. The simplest option, 'Low Complexity', would require only a high ESR cap at the output. This means that the BOM count will be small, but the output voltage ripple will be quite large. The 'Optimal Solution' would require a feed-forward cap in parallel with the upper feedback resistor to AC couple the ripple to the feedback node. This increases the BOM count slightly, but now we have more control over the output voltage ripple. If the output voltage requirement is very tight, then the best option is to go for the 'Low Output Ripple' solution. In this option we can go with very low ESR output caps and have very good control over the output voltage ripple.
- 2. Master key: 899DA37B8B0572B838E91FF5840BDDB6[v1]
- 3. LM5008A Product Folder: http://www.ti.com/product/LM5008A: contains the data sheet and other resources.

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